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CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to: Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450, on the below date:
Date: 7/26/05 Name: Anthony P. Curtis, Ph.D., 46,193 Signature: [Signature]

BRINKS
HOFER
GILSON
& LIONE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln. of: Kuang Chien et al.

Appln. No.: 10/680,509

Filed: October 7, 2003

For: Adhesive Bonding with Low Temperature
Grown Amorphous or Polycrystalline
Compound Semiconductor

Examiner: Hoa B. Trinh

Art Unit: 2814

Attorney Docket No: 10322/57

Mail Stop Amendment
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL

Sir:

Attached is/are:

- ☒ Transmittal Cover Letter (1p. Filed in Dup.); Supplemental Information Disclosure Statement and PTO Form 1449 (3pp.); 6 Non-U.S. Prior Art (B5-B10)
- ☒ Return Receipt Postcard

Fee calculation:

- ☒ No additional fee is required.
- ☐ Small Entity.
- ☐ An extension fee in an amount of \$_____ for a _____-month extension of time under 37 C.F.R. § 1.136(a).
- ☐ A petition or processing fee in an amount of \$_____ under 37 C.F.R. § 1.17(_____).
- ☐ An additional filing fee has been calculated as shown below:

					Small Entity			Not a Small Entity	
	Claims Remaining After Amendment		Highest No. Previously Paid For	Present Extra	Rate	Add'l Fee	or	Rate	Add'l Fee
Total		Minus			x \$25=			x \$50=	
Indep.		Minus			x 100=			x \$200=	
First Presentation of Multiple Dep. Claim					+\$180=			+\$360=	
					Total	\$		Total	\$

Fee payment:

- ☐ A check in the amount of \$_____ is enclosed.
- ☐ Please charge Deposit Account No. 23-1925 in the amount of \$_____. A copy of this Transmittal is enclosed for this purpose.
- ☐ Payment by credit card in the amount of \$_____ (Form PTO-2038 is attached).
- ☒ The Director is hereby authorized to charge payment of any additional filing fees required under 37 CFR § 1.16 and any patent application processing fees under 37 CFR § 1.17 associated with this paper (including any extension fee required to ensure that this paper is timely filed), or to credit any overpayment, to Deposit Account No. 23-1925.

Date

7/26/05

Respectfully submitted,

[Signature]
Anthony P. Curtis, Ph.D. (Reg. No. 46,193)



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For: ADHESIVE BONDING WITH
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COMPOUND
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Examiner: Hoa B. Trinh

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and §§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(c), Applicants hereby cite the following reference(s):

No.	Date of Publication	Patentee/Applicant/Assignee
5,920,766	July 6, 1999	Floyd
5,858,855	January 12, 1999	Kobayashi
5,854,090	December 29, 1998	Iwai et al.
5,233,216	August 3, 1993	Inoue et al.
FOREIGN PATENT DOCUMENTS		
EP 1 246 238 A2	October 2, 2002	EPO
JP 10-12506	January 16, 1998	Japan
OTHER ART – NON PATENT LITERATURE DOCUMENTS		
Copy of International Search Report from corresponding PCT patent application number PCT/US2004/031254.		
K.L. Chang, G.W. Pickrell, K.Y. Cheng and K.C. Hsieh, <i>Wafer Bonding With Low-Temperature-Grown (Ga,P) as an Adhesive Material</i> , pgs. 906-910, Institute of Physics Publishing, Semiconductor Science and Technology, 2004		
K.D. Choquette, K.M. Geib, B. Roberds, H.Q. Hou, R.D. Twesten and B.E. Hammons, <i>Short Wavelength Bottom-Emitting Vertical Cavity Lasers Fabricated Using Wafer Bonding</i> , pgs. 1404-1405, IEEE, Electronic Letters, Vol. 34, No. 14, July 9, 1998.		
K. Mori, K. Tokutome and S. Sugou, <i>Low-Threshold Pulsed Operation of Long-wavelength Lasers on Si Fabricated By Direct Bonding</i> , pgs. 284-285, IEEE Electronic Letters, Vol. 31, No. 4, February 16, 1995.		

Applicants are enclosing Form PTO-1449 (one sheet), along with a copy of each listed reference for which a copy is required under 37 C.F.R. §1.98(a)(2). As each of the listed references is in English, no further commentary is believed to be necessary, 37 C.F.R §1.98(a)(3). Applicants respectfully request the Examiner's

consideration of the above reference(s) and entry thereof into the record of this application.


By submitting this Statement, Applicants are attempting to fully comply with the duty of candor and good faith mandated by 37 C.F.R. §1.56. As such, this Statement is not intended to constitute an admission that any of the enclosed references, or other information referred to therein, constitutes "prior art" or is otherwise "material to patentability," as that phrase is defined in 37 C.F.R. §1.56(a).

For purposes of 37 C.F.R. §1.704(d), Applicants certify that each item of information contained in this Statement was first cited in any communication from a foreign patent office in a counterpart application, and that this communication was not received by any individual designated in 37 C.F.R. §1.56(c) more than thirty days prior to the filing of this Statement (a copy of any foreign communication first citing a listed reference is attached for the Examiner's reference).

Applicants certify pursuant to 37 C.F.R. §1.97(e)(1) that each item of information in this Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Statement (a copy of any foreign communication first citing a listed reference is attached for the Examiner's reference). Accordingly, Applicants have calculated no fee to be due in connection with the filing of this Statement. However, the Director is authorized to charge any fee deficiency associated with the filing of this Statement to a deposit account, as authorized in the Transmittal accompanying this Statement.

7/26/05
Date

Respectfully submitted,


Anthony P. Curtis, Ph.D.
(Reg. No. 46,193)



FORM PTO-1449	SERIAL NO. 10/680,509	CASE NO. 10322/57
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE October 7, 2003	GROUP ART UNIT 2814
(use several sheets if necessary)		APPLICANT(S): Kuang Chien et al.

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
	B1	5,920,766	July 6, 1999	Floyd		
	B2	5,858,855	January 12, 1999	Kobayashi		
	B3	5,854,090	December 29, 1998	Iwai et al.		
	B4	5,233,216	August 3, 1993	Inoue et al.		

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO
	B5	EP 1 246 238 A2	October 2, 2002	EPO		
	B6	JP 10-12506	January 16, 1998	Japan		

OTHER ART – NON PATENT LITERATURE DOCUMENTS

EXAMINER INITIAL		(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.
	B7	Copy of International Search Report from corresponding PCT patent application number PCT/US2004/031254.
	B8	K.L. Chang, G.W. Pickrell, K.Y. Cheng and K.C. Hsieh, <i>Wafer Bonding With Low-Temperature-Grown (Ga,P) as an Adhesive Material</i> , pgs. 906-910, Institute of Physics Publishing, Semiconductor Science and Technology, 2004
	B9	K.D. Choquette, K.M. Geib, B. Roberds, H.Q. Hou, R.D. Twesten and B.E. Hammons, <i>Short Wavelength Bottom-Emitting Vertical Cavity Lasers Fabricated Using Wafer Bonding</i> , pgs. 1404-1405, IEEE, Electronic Letters, Vol. 34, No. 14, July 9, 1998.
	B10	K. Mori, K. Tokutome and S. Sugou, <i>Low-Threshold Pulsed Operation of Long-wavelength Lasers on Si Fabricated By Direct Bonding</i> , pgs. 284-285, IEEE Electronic Letters, Vol. 31, No. 4, February 16, 1995.

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.